

General Description

The HIRFB4321PBF use advanced SGT MOSFET

technology to provide low RDS(ON), low gate charge,

fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness.



TO-220

General Features

V_{DS} =150V I_D =120A

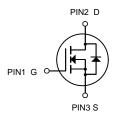
 $R_{DS(ON)}$ < 11.5m Ω @ V_{GS} =10V

Applications

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)	
HIRFB4321PBF	TO-220	HXY MOSFET	50	

Absolute Maximum Ratings at T_j=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	VDS	150	V
Gate source voltage	VGS	±20	V
Continuous drain current ¹⁾	ID	120	Α
Pulsed drain current ²⁾	ID, pulse	352	Α
Power dissipation ³⁾	P _D	178.6	W
Single pulsed avalanche energy ⁵⁾	EAS	204.8	mJ
Operation and storage temperature	Tstg, Tj	-55 to 150	°C
Thermal resistance, junction-case	RθJC	0.7	°C/W
Thermal resistance, junction-ambient ⁴⁾	RθJA	52	°C/W



N-SGT Enhancement Mode MOSFET

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics								
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	150	-	-	V	
Gate-body Leakage Current	Gate-body Leakage Current		V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain	T _J =25°C		V _{DS} = 150V, V _{GS} = 0V	-	-	1	μА	
Current	T _J =100°C	IDSS		-	-	100		
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	3	4	V	
Drain-Source On-Resistance	Drain-Source On-Resistance ⁴		V _{GS} = 10V, I _D = 20A	-	9.5	11.5	mΩ	
Forward Transconductance ⁴		g _{fs}	V _{DS} = 10V, I _D = 20A	-	69	-	S	
Dynamic Characteristic	s ⁵					•		
Input Capacitance		C _{iss}		-	3310	-	pF	
Output Capacitance		Coss	V _{DS} = 75V, V _{GS} =0V, f =1MHz	-	268	-		
Reverse Transfer Capacitance		Crss		-	9.4	-		
Gate Resistance		R _g	f = 1MHz	-	3.2	-	Ω	
Switching Characteristi	CS ⁵			1		•		
Total Gate Charge		Qg		-	45	-	nC	
Gate-Source Charge		Qgs	$V_{GS} = 10V, V_{DS} = 75V,$ $I_{D} = 20A$	-	15	-		
Gate-Drain Charge	Gate-Drain Charge			-	8.5	-		
Turn-On Delay Time	Turn-On Delay Time			-	16	-	. ns	
Rise Time		t _r	$V_{GS} = 10V$, $V_{DD} = 75V$, $R_G = 3\Omega$, $I_{D} = 20A$	-	12	-		
Turn-Off Delay Time		t _{d(off)}		-	30	-		
Fall Time		t _f		-	18	-		
Body Diode Reverse Recovery Time		t _{rr}		-	76	-	ns	
Body Diode Reverse Recovery Charge		Qrr	- I _F =20A, dl/dt=100A/μs	-	182	-	nC	
Drain-Source Body Diode Characteristics								
Diode Forward Voltage ⁴	Diode Forward Voltage ⁴		I _S = 20A, V _{GS} = 0V	-	-	1.2	V	
Continuous Source Current	T _C =25°C	Is	-	-	-	120	Α	

Notes:

- 1. Repetitive rating, pulse width limited by junction temperature $T_{\text{J(MAX)}}$ =150°C
- 2. The EAS data shows Max. rating . The test condition is V_{DD} =50V, V_{GS} =10V,L=0.4mH, I_{AS} =32A.
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

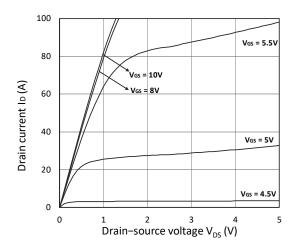


Figure 1. Output Characteristics

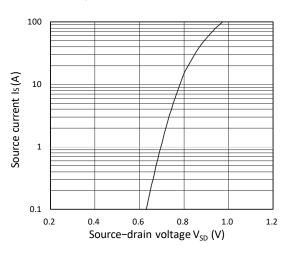


Figure 3. Forward Characteristics of Reverse

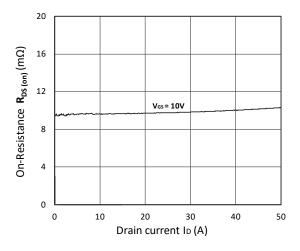


Figure 5. $R_{DS(ON)}$ vs. I_D

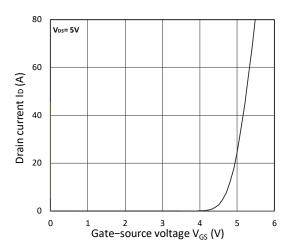


Figure 2. Transfer Characteristics

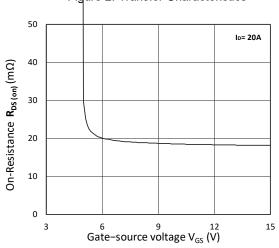


Figure 4. $R_{\text{DS}(\text{ON})}\,$ vs. V_{GS}

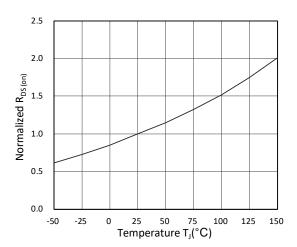
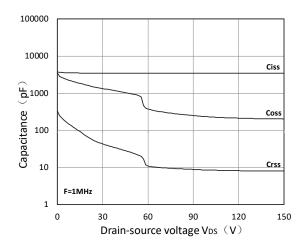


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



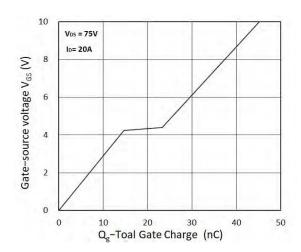
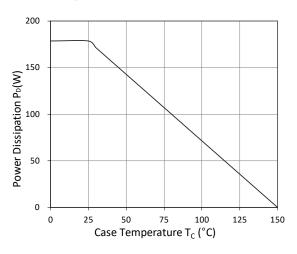


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics



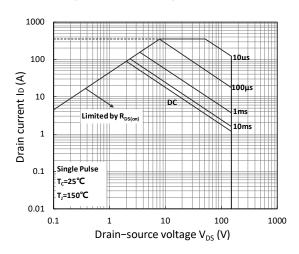


Figure 9. Power Dissipation

Figure 10. Safe Operating Area

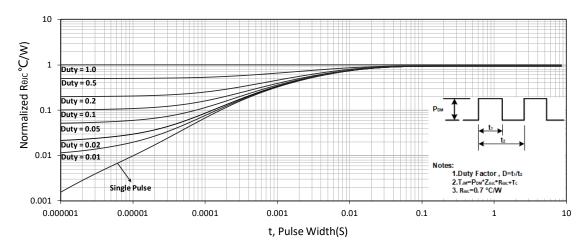


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

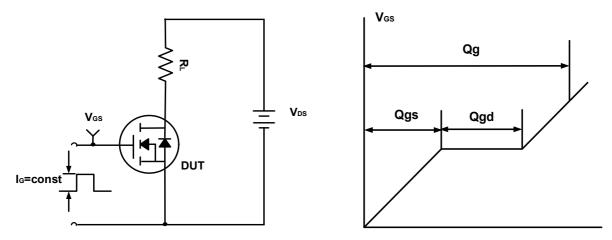


Figure A. Gate Charge Test Circuit & Waveforms

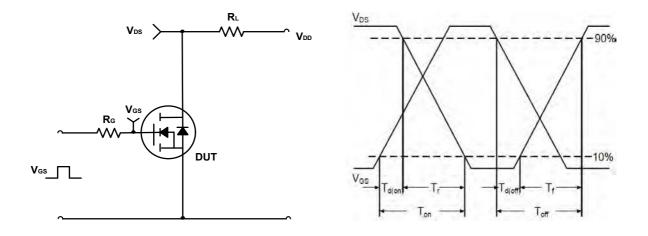


Figure B. Switching Test Circuit & Waveforms

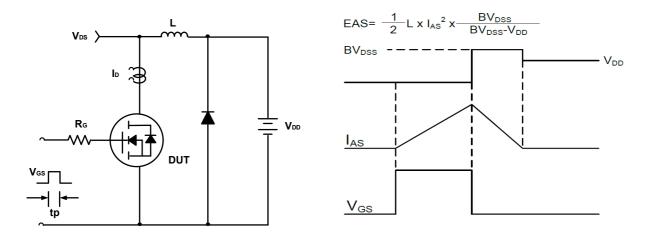
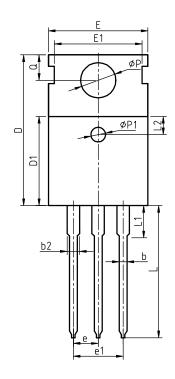


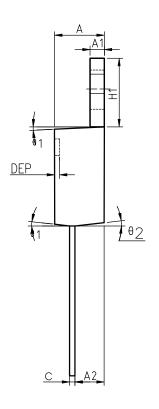
Figure C. Unclamped Inductive Switching Circuit & Waveforms



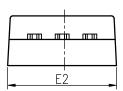
Package Information

TO-220





COMMON DIMENSIONS



SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
Α	4.40	4.57	4.70	0.173	0.180	0.185
A1	1. 27	1.30	1.33	0.050	0.051	0.052
A2	2.35	2.40	2.50	0.093	0.094	0.098
b	0.77	0.80	0.90	0.030	0.031	0.035
b2	1. 17	1.27	1.36	0.046	0.050	0.054
С	0.48	0.50	0.56	0.019	0.020	0.022
D	15.40	15.60	15.80	0.606	0.614	0.622
D1	9.00	9.10	9. 20	0.354	0.358	0.362
DEP	0.05	0.10	0. 20	0.002	0.004	0.008
E	9.80	10.00	10.20	0.386	0.394	0.402
E1	-	8.70	-	-	0.343	-
E2	9.80	10.00	10.20	0.386	0.394	0.402
е		2.54	BSC		0.100	BSC
e1		5.08	BSC		0.200	BSC
H1	6.40	6.50	6.60	0. 252	0.256	0.260
L	12.75	13.50	13.65	0.502	0.531	0.537
L1	-	3. 10	3.30	-	0.122	0.130
L2		2.50	REF		0.098	REF
Р	3.50	3.60	3.63	0.138	0.142	0.143
P1	3.50	3.60	3.63	0.138	0.142	0.143
Q	2.73	2.80	2.87	0. 107	0.110	0.113
θ 1	5°	7°	9°	5°	7°	9°
θ 2	1°	3°	5°	1°	3°	5°
θ 3	1°	3°	5°	1°	3°	5°



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